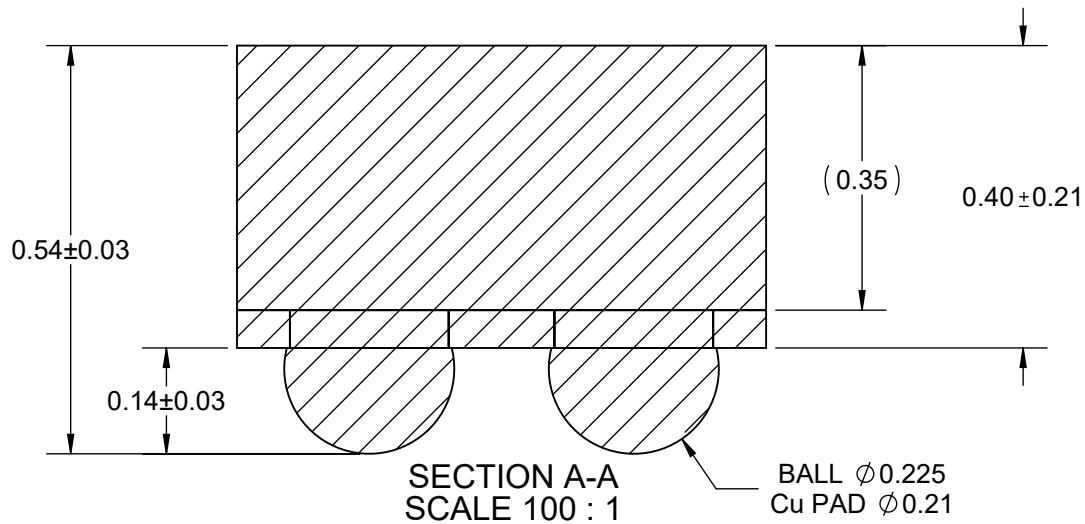
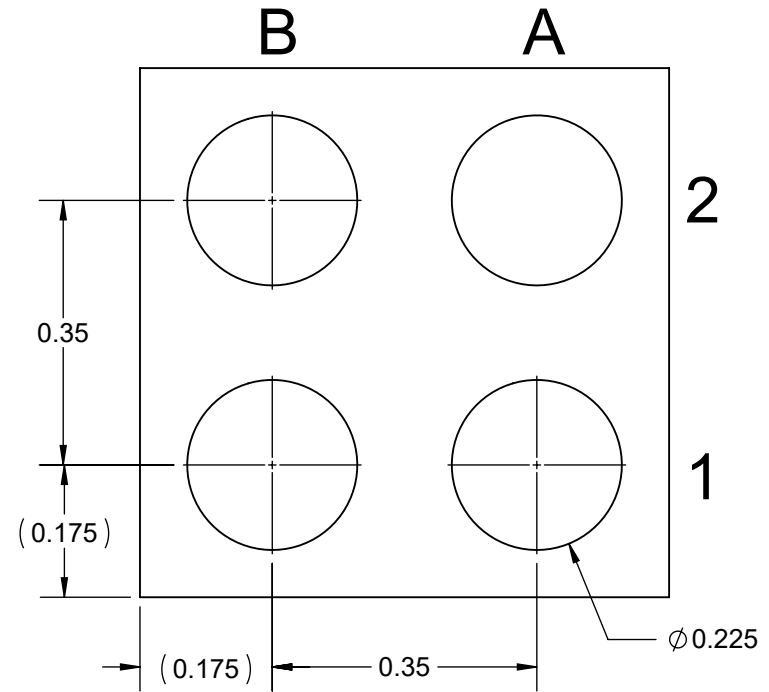
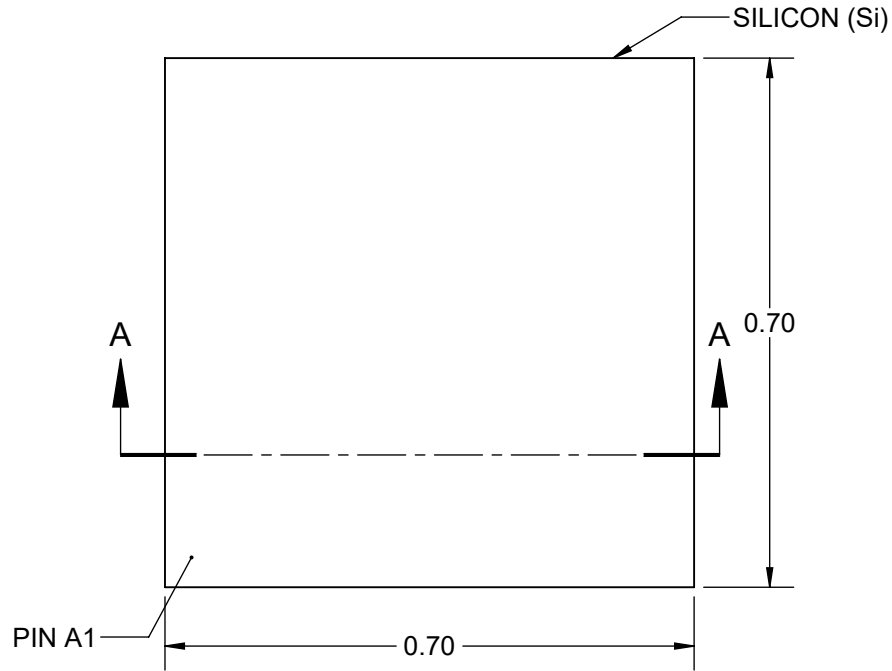


TOP VIEW

BALL VIEW



Notes: (Unless Otherwise Specified).

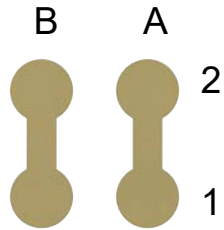
- 1) DIMENSIONS: mm
- 2) SOLDER BALL ALLOY: SAC305 (Sn96.5/Ag3.0/Cu0.5).
- 3) BALL DIAMETER (BEFORE REFLOW) $\phi 0.225\text{mm} \pm 0.03$.
- 4) NON-SOLDER MASK DEFINED PAD.
- 5) PAD Cu DIAMETER: $\phi 0.21\text{mm}$.
- 6) SUBSTRATE MATERIAL: Si (SILICON).
- 7) DAISY CHAIN PATTERN (SEE PAGE 2).

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
WLP4T.35C-DC022D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES

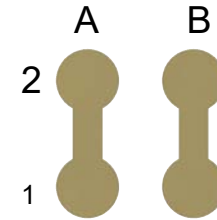
APPROVALS	DATE	TopLine [®]		
DRAWN T. Au	9/2/2023			
ENG M. Hart	9/2/2023	TITLE WLP4T.35C-DC022D 4 BALL P=0.35mm		
MFG		SCALE	SIZE	DRAWING NO.
QA		40:1	A	570220
CUST				REV A
REVISED		DO NOT SCALE DRAWING		SHEET 1 OF 5

DAISY CHAIN PATTERN

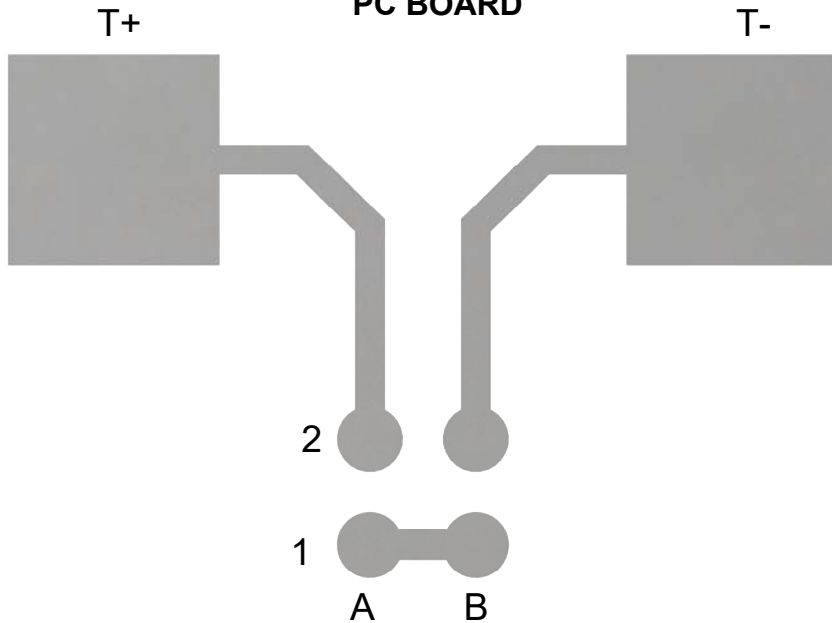
BALL VIEW



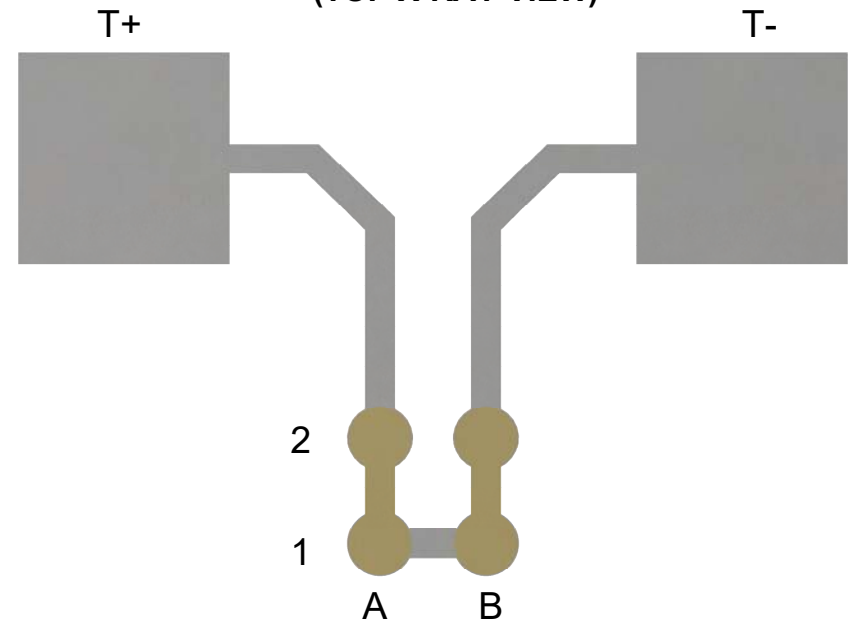
**BOTTOM SIDE
(TOP X-RAY VIEW)**



PC BOARD



**AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)**

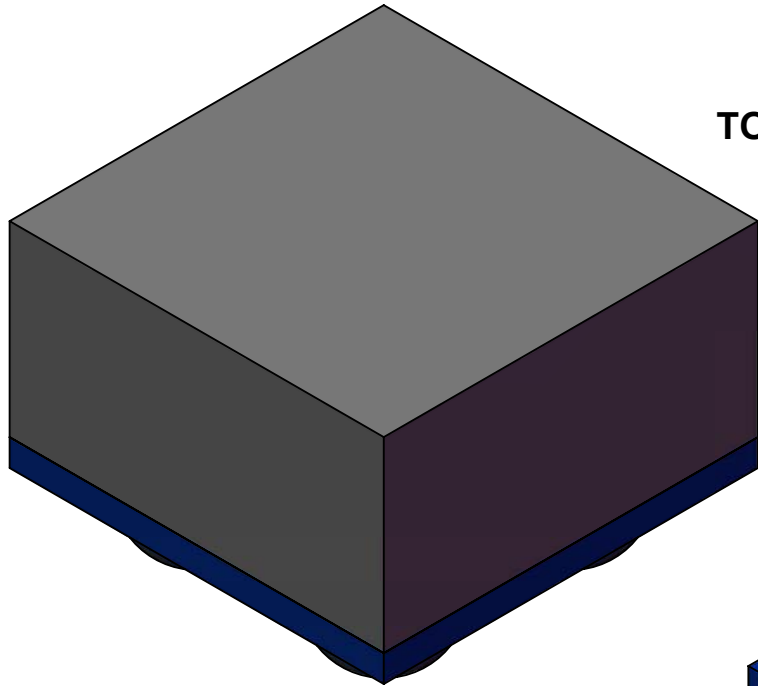


Notes:

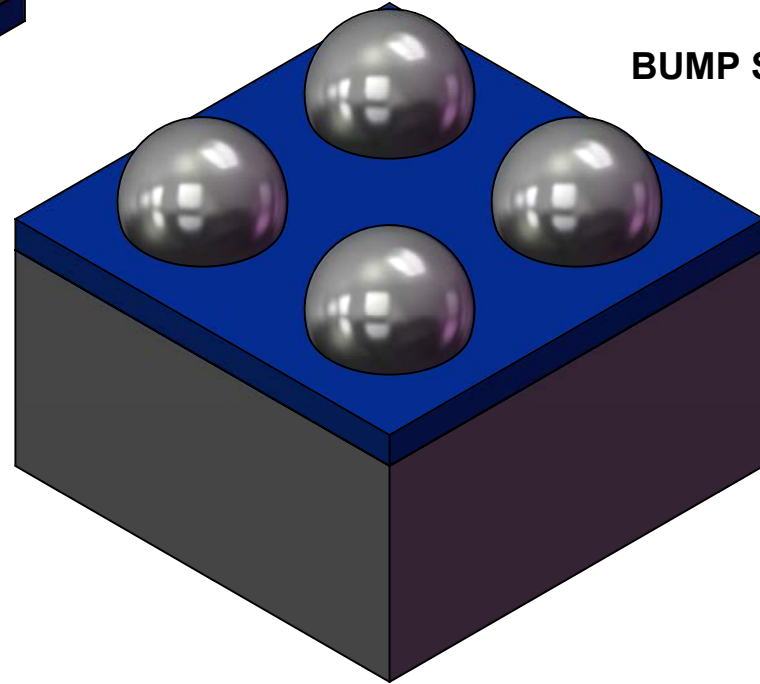
- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER: $\varnothing 0.21\text{mm}$ (8.2 mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH: 0.10mm (4 mil).

TopLine[®]			
TITLE		WLP4T.35C-DC022D 4 BALL P=0.35mm	
SCALE	SIZE	DRAWING NO.	REV
25:1	A	570220	A
DO NOT SCALE DRAWING			SHEET 2 OF 5

MODEL



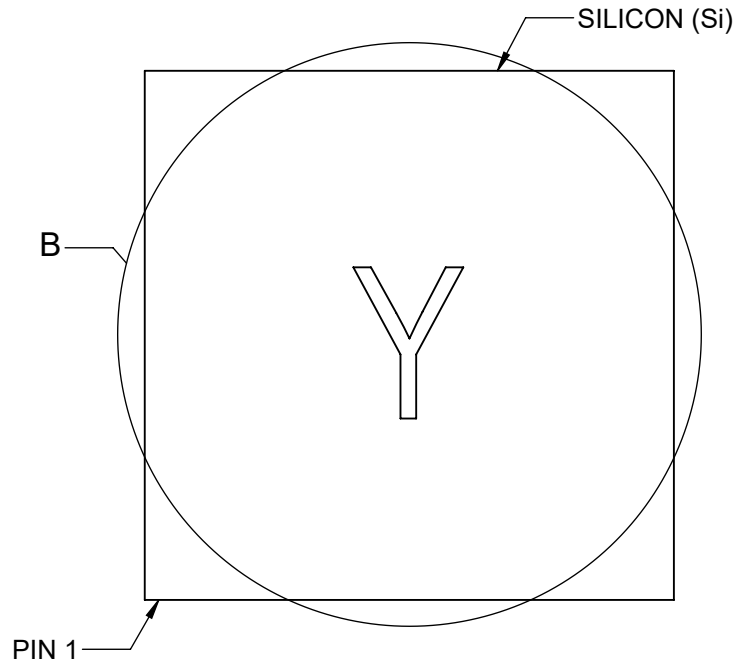
TOP



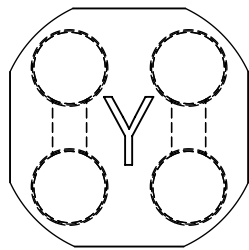
BUMP SIDE

TopLine[®]			
TITLE		WLP4T.35C-DC022D 4 BALL P=0.35mm	
SCALE	SIZE	DRAWING NO.	REV
40:1	A	570220	A
DO NOT SCALE DRAWING			SHEET 3 OF 5

TOP VIEW



EXAMPLE ORIENTATION OF MARKING ON WLP

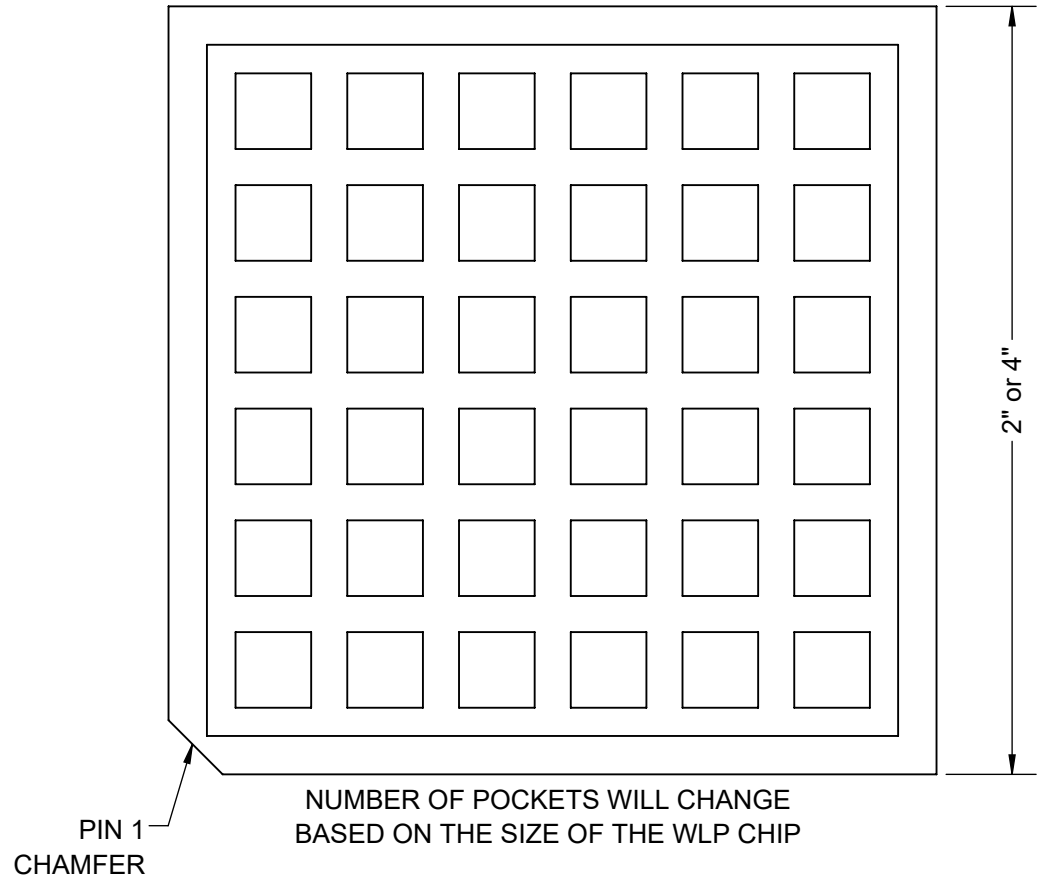


DAISY CHAIN ORIENTATION
DETAIL B
SCALE 45 : 1

MARKING CODE	
PITCH	LETTER
0.35mm	Y

* SUBJECT TO CHANGE

**TYPICAL WAFFLE PACK
IC CHIP TRAY SCALE = 2:1**



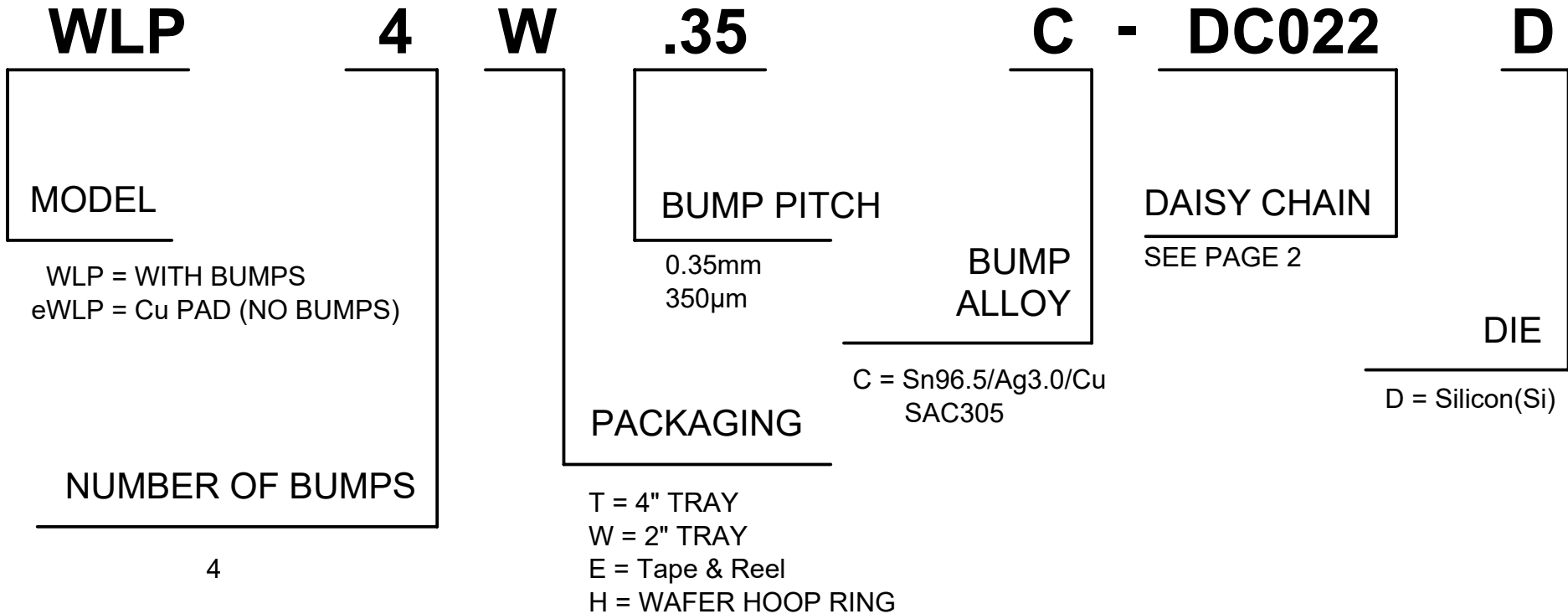
NUMBER OF POCKETS WILL CHANGE
BASED ON THE SIZE OF THE WLP CHIP

Notes: (Unless Otherwise Specified).

- 1) EXAMPLE OF TOP SIDE LASER MARKING.
- 2) ORIENT LETTERS FOR LOCATION OF PIN A1 CORNER.
- 3) ALLOWABLE LETTER MARKING: A, F, T, M, L, Y, AND P.
- 4) SINGLE LETTER IS REPEATED MULTIPLE TIMES ACROSS TOP SIDE.
- 5) DAISY CHAIN IS HIDDEN UNDER RESIN ON BALL SIZE.
- 6) TOP SIDE DOES NOT HAVE A DOT FOR LOCATION OF PIN A1.
- 7) LETTERS ARE NOT MARKED ON BOTTOM (BALL) SIDE.

TopLine[®]			
TITLE		WLP4T.35C-DC022D 4 BALL P=0.35mm	
SCALE	SIZE	DRAWING NO.	REV
30:1	A	570220	A
DO NOT SCALE DRAWING			SHEET 4 OF 5

PART NUMBER SYSTEM



PART NUMBER	PACKAGING	QTY
WLP4W.35C-DC022D	2" CHIP TRAY	400
WLP4T.35C-DC022D	4" CHIP TRAY	CALL
WLP4E.35C-DC022D	T&R	1000
WLP4H.35C-DC022D	WAFER RING	CALL

TopLine[®]			
TITLE		WLP4T.35C-DC022D 4 BALL P=0.35mm	
SCALE	SIZE	DRAWING NO.	REV
30:1	A	570220	A
DO NOT SCALE DRAWING			SHEET 5 OF 5